

SANYO Semiconductors

DATA SHEET

An ON Semiconductor Company

Features

· Low collector-to-emitter saturation voltage

· Very small size making it easy to provide highdensity, small-sized hybrid IC's

Specifications

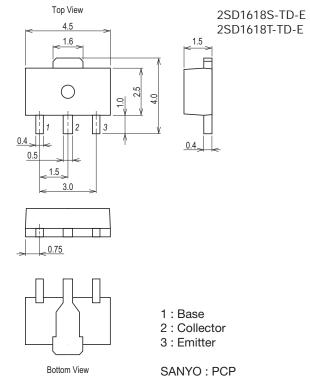
Absolute Maximum Ratings at Ta=25°C

3				
Parameter	Symbol	Conditions	Ratings	Unit
Collector-to-Base Voltage	VCBO		20	V
Collector-to-Emitter Voltage	VCEO		15	V
Emitter-to-Base Voltage	VEBO		5	V
Collector Current	IC		0.7	А
Collector Current (Pulse)	ICP		1.5	А
Collector Dissipation	PC		500	mW
		When mounted on ceramic substrate (250mm ² ×0.8mm)	1.3	W
Junction Temperature	Tj		150	°C
Storage Temperature	Tstg		-55 to +150	°C

Package Dimensions

unit : mm (typ) 7007B-004





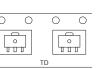
Product & Package Information

- Package
- JEITA, JEDEC : SC-62, SOT-89, TO-243

: PCP

• Minimum Packing Quantity : 1,000 pcs./reel

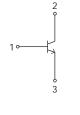
Packing Type: TD





Marking

Electrical Connection



onnection

80812 TKIM/92098HA (KT)/4017KI/0216AT/2065MY, TS No.1784-1/6

Electrical Characteristics at Ta=25°C

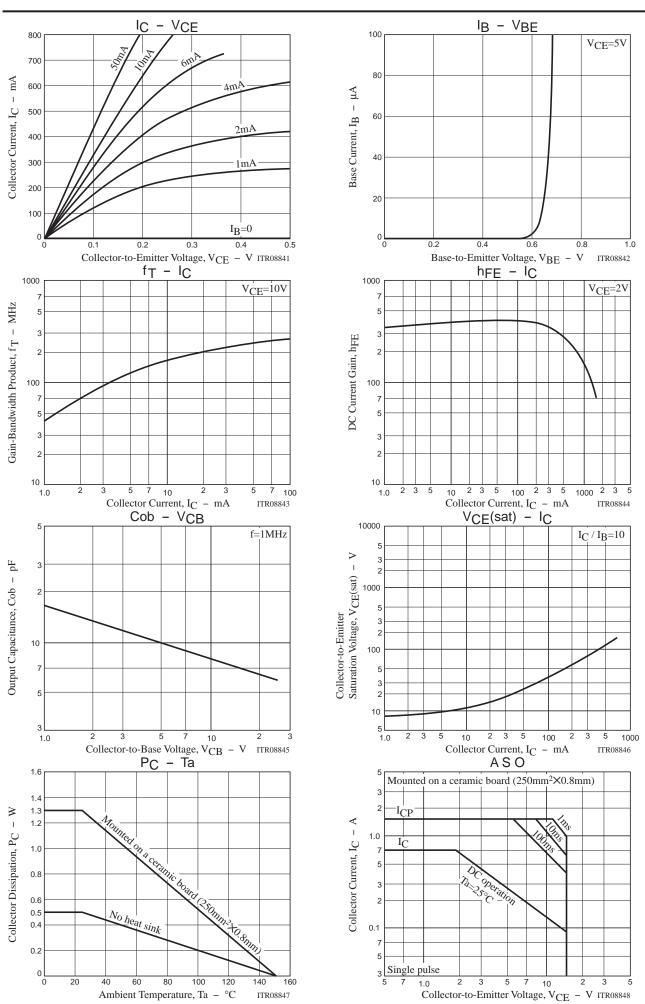
Parameter	Sumbol	Conditions	Ratings			1.1	
Parameter	Symbol	Symbol Conditions -		typ	max	Unit	
Collector Cutoff Current	ICBO	VCB=15V, IE=0A			0.1	μΑ	
Emitter Cutoff Current	IEBO	V _{EB} =4V, I _C =0A			0.1	μΑ	
DC Current Gain	h _{FE} 1	V _{CE} =2V, I _C =50mA	140*		560*		
	h _{FE} 2	V _{CE} =2V, I _C =500mA	60				
Gain-Bandwidth Product	fT	VCE=10V, IC=50mA		250		MHz	
Collector-to-Emitter Saturation Voltage	V _{CE} (sat)1	IC=5mA, IB=0.5mA		10	25	mV	
	V _{CE} (sat)2	I _C =100mA, I _B =10mA		30	80	mV	
Base-to-Emitter Saturation Voltage	V _{BE} (sat)	I _C =100mA, I _B =10mA		0.8	1.2	V	
Collector-to-Base Breakdown Voltage	V(BR)CBO	IC=10μA, IE=0A	20			V	
Collector-to-Emitter Breakdown Voltage	V(BR)CEO	IC=1mA, RBE=∞	15			V	
Emitter-to-Base Breakdown Voltage	V(BR)EBO	I _E =10μA, I _C =0A	5			V	
Output Capacitance	Cob	V _{CB} =10V, f=1MHz		8		pF	

 * : The 2SD1618 is classified by 50mA hFE as follows :

Rank	S	Т	U		
hFE	140 to 280	200 to 400	280 to 560		

Ordering Information

Device	Package	Shipping	memo
2SD1618S-TD-E	PCP	1,000pcs./reel	Pb Free
2SD1618T-TD-E	PCP	1,000pcs./reel	PD Flee



Bag Packing Specification 2SD1618S-TD-E, 2SD1618T-TD-E

1. Packing Format

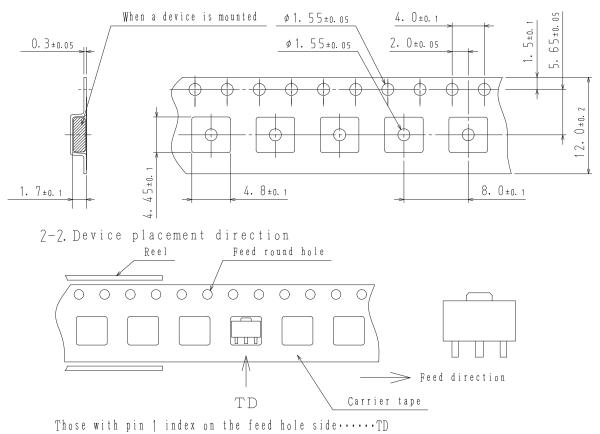
Package Name	Carrier Tape	Maximum Number of devices contained (pcs)			Packing format		
	Туре	Reel	Inner box	Outer box	Inner BOX (C-1) Outer BOX (A-7)		
РСР	РСР	1,000	4,000	24,000	4 reels contained 6 inner boxes contained		
					Dimensions:mm (external) Dimensions:mm (external)		
					183×72×185 440×195×210		
			Reel	label, I	nner box label <u>Outer box label</u>		
Packing method (and to infinity) The form of a label may change in physi					n i t : mm) The form of a label may change in physical distribution process		
0	>		<	6	59 108		
	Orig	No. tity	-> (17 -> (00 (2) -> As NOTE	н полини поли D LOT О О атту О О и полини поли ягту О О и полини полини ягту О О и полини во С и О и Полини и полини во С и Полини и полини во С и С и О и О и С и О и О и О и О и О и О и О и О	DIFFUSION:****) SPECIAL SPEC		
				Label LEAD FRH			

LEAD FREE 4

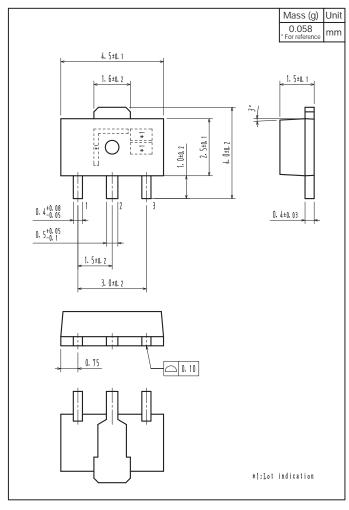
JEITA Phase 3

2. Taping configuration

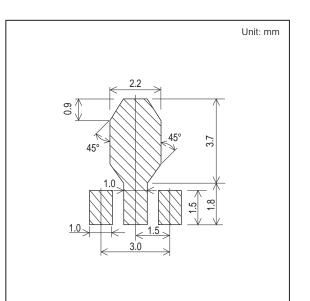
2-1. Carrier tape size (unit:mm)



Outline Drawing 2SD1618S-TD-E, 2SD1618T-TD-E



Land Pattern Example



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